

What is claimed is:

1. A method of coupling a semiconductor die with a next level package, comprising:
 - providing at least one interconnect;
 - arranging the semiconductor die, the next level package, and the at least one interconnect such that the at least one interconnect is disposed so as to be capable of joining the semiconductor die to the next level package;
 - providing an inductor capable of generating an electromagnetic flux;
 - generating an electromagnetic flux;
 - exposing the semiconductor die to the electromagnetic flux to induce heating in the semiconductor die; and
 - heating the semiconductor die to couple the semiconductor die with the next level package.
2. The method of claim 1, wherein the heating preferentially heats the semiconductor die over the next level package.
3. The method of claim 2, wherein generating an electromagnetic flux comprises providing an alternating electric current having a frequency exceeding 1 megahertz.

4. The method of claim 3, wherein generating an electromagnetic flux comprises providing an alternating electric current having a frequency of approximately 13.2 megahertz.
5. The method of claim 3, wherein the at least one interconnect comprises an array of interconnects.
6. The method of claim 5, wherein the array of interconnects is formed on the semiconductor die.
7. The method of claim 6, further comprising arranging the inductor such that the semiconductor die is interposed between the inductor and the next level package.
8. The method of claim 7, wherein the next level package is a substrate.
9. The method of claim 8, wherein the next level package is a flexible substrate.
10. The method of claim 7, wherein the next level package is an interposer.

11. The method of claim 7, wherein the next level package is a printed wiring board.

12. The method of claim 6, further comprising arranging the inductor such that the next level package is interposed between the inductor and the semiconductor die.

13. The method of claim 12, wherein the next level package is a substrate.

14. The method of claim 13, wherein the next level package is a flexible substrate.

15. The method of claim 12, wherein the next level package is an interposer.

16. The method of claim 12, wherein the next level package is a printed wiring board.

17. A method of coupling a semiconductor die with a next level package, comprising:

providing at least one interconnect;

arranging the semiconductor die, the next level package, and the at least

one interconnect such that the at least one interconnect is disposed so as to be capable of joining the semiconductor die to the next level package;

providing an inductor capable of generating an electromagnetic flux;

generating an electromagnetic flux;

exposing the at least one interconnect to the electromagnetic flux to induce heating in the at least one interconnect; and

heating the at least one interconnect to couple the semiconductor die with the next level package.

18. The method of claim 17, wherein the heating preferentially heats the at least one interconnect over the at least one next level package

19. The method of claim 18, wherein the heating preferentially heats the at least one interconnect over the semiconductor die.

20. The method of claim 19, wherein generating an electromagnetic flux comprises providing an alternating electric current having a frequency exceeding 1 megahertz.

21. The method of claim 20, wherein generating an electromagnetic flux comprises providing an alternating electric current having a frequency of approximately 13.2 megahertz.

22. The method of claim 20, wherein the at least one interconnect comprises an array of interconnects.

23. The method of claim 22, wherein the array of interconnects is formed on the semiconductor die.

24. The method of claim 23, further comprising arranging the inductor such that the semiconductor die is interposed between the inductor and the next level package.

25. The method of claim 24, wherein the next level package is a substrate.

26. The method of claim 25, wherein the next level package is a flexible substrate.

27. The method of claim 24, wherein the next level package is an interposer.

28. The method of claim 24, wherein the next level package is a printed wiring board.

29. The method of claim 23, further comprising arranging the inductor such that the next level package is interposed between the inductor and the semiconductor die.
30. The method of claim 29, wherein the next level package is a substrate.
31. The method of claim 30, wherein the next level package is a flexible substrate.
32. The method of claim 29, wherein the next level package is an interposer.
33. The method of claim 29, wherein the next level package is a printed wiring board.